

In the Claims:

Please enter the following amended claim 11:

11. (Once Amended) A structure comprising:

a laminate substrate having a top surface;

A¹ a first semiconductor die and a second semiconductor die attached to said top surface of said laminate substrate;

a first antenna element situated on said top surface of said laminate substrate, said first antenna element coupled to a first laminate substrate bond pad;

a second antenna element situated on said top surface of said laminate substrate, said second antenna element coupled to a second laminate substrate bond pad;

a first bonding wire providing an electrical connection between said first laminate substrate bond pad and a semiconductor die bond pad on said first semiconductor die;

a second bonding wire providing an electrical connection between said second laminate substrate bond pad and a semiconductor die bond pad on said second semiconductor die.
